

## APPARATUS AND METHOD FOR REPAIRING ELECTRONIC PACKAGES

### ABSTRACT

A multi chip module substrate arranged with repair vias and repair lines  
5 extending between repair vias of the chip sites of the module by which repairs can be  
effected to overcome defects in the module circuits and a method for effecting the repairs  
of defects in the circuits of this module. A defect can occur in any one of a first signal  
via, a second signal via, and a circuit line extending between and intended to electrically  
connect the first signal via and the second signal via. After a defective circuit is  
10 identified, the signal vias of the circuit are isolated. Then, the first signal via of the  
defective circuit is electrically connected to that repair via of the chip site having the first  
signal via that is connected to that repair via of the chip site having the second signal via  
and the second signal via of the defective circuit is electrically connected to that repair via  
of the chip site having the second signal via that is connected to that repair via of the chip  
15 site having the first signal via.